# Siliup Semiconductor

# **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(on)TYP</sub>	l <sub>D</sub>
200V	8mΩ@10V	150A



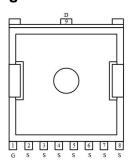
#### **Feature**

- Fast Switching
- Low Gate Charge and Rdson
- Low Reverse transfer capacitances
- 100% Single Pulse avalanche energy Test

## **Applications**

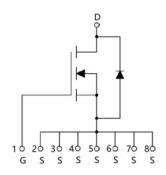
- High Speed Power switching
- DC-DC Converter
- Power Management

# **Package**



**TOLL** 

# Circuit diagram



### **Marking**



SP020N08GHTO: Product code
\*\*: Week code

#### **Order Information**

Device	Package	Unit/Tape
SP020N08GHTO	TOLL	2000

200V N-Channel Power MOSFET

# Absolute maximum ratings (Ta=25°C,unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V <sub>DS</sub>	200	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Continuous Drain Current (Tc=25°C)	I <sub>D</sub>	150	Α
Continuous Drain Current (Tc=100°C)	I <sub>D</sub>	100	Α
Pulsed Drain Current	I <sub>DM</sub>	600	Α
Single Pulse Avalanche Energy <sup>1</sup>	Eas	1156	mJ
Power Dissipation (Tc=25°C)	P <sub>D</sub>	340	W
Thermal Resistance Junction-to-Case	R <sub>eJC</sub>	0.37	°C/W
Storage Temperature Range	T <sub>STG</sub>	-55 to 150	$^{\circ}$
Operating Junction Temperature Range	TJ	-55 to 150	$^{\circ}$ C

# Electrical characteristics (Ta=25°C, unless otherwise noted)

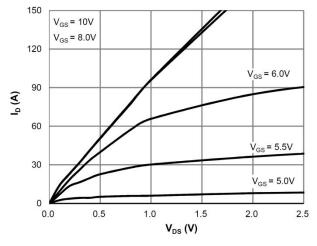
Characteristics	Symbol	Test Condition	Min	Тур	Max	Unit
Static Characteristics	•		'	•		
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	ID = 250µA, VGS = 0V	200	220	-	٧
Drain Cut-Off Current	I <sub>DSS</sub>	VDS = 160V, VGS = 0V	-	-	1	
Gate Leakage Current	I <sub>GSS</sub>	VGS = ±20V, VDS = 0V	-	-	±0.1	μA
Gate Threshold Voltage	$V_{GS(th)}$	VDS = VGS, ID = 250μA	2.0	3.0	4.0	V
Drain-Source ON Resistance	R <sub>DS(ON)</sub>	VGS = 10V, ID = 20A	-	8	9.5	mΩ
Dynamic Characteristics						
Input Capacitance	Ciss	VDS =100V, VGS = 0V, f = 1.0MHz	-	5300	-	
Output Capacitance	Coss		-	410	-	pF
Reverse Transfer Capacitance	C <sub>rss</sub>		-	27	-	
Total Gate Charge	Qg		-	78	-	nC
Gate-Source Charge	Q <sub>gs</sub>	VDS=100V , VGS=10V , ID=20A	-	28	-	
Gate-Drain Charge	$Q_{gd}$			17	-	
Switching Characteristics						
Turn-On Delay Time	t <sub>d(on)</sub>		-	23	-	
Rise Time	t <sub>r</sub>	VGS = 10V, VDS =100V, RL=3.5Ω,	-	48	-	nS
Turn-Off Delay Time	$t_{d(off)}$	RG = 6.0Ω	-	63	-	
Fall Time	t <sub>f</sub>		-	19	-	
<b>Drain-Source Body Diode Characteris</b>	tics					
Source-Drain Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 1A, VGS = 0V	-	-	1.2	V
Maximum Body-Diode Continuous Current	ls		-	-	150	Α
Body Diode Reverse Recovery Time	Trr	I <sub>S</sub> = 50A, dI <sub>F</sub> /dt = 100A/us		128	-	nS
Body Diode Reverse Recovery Charge	Qrr			643	-	nC

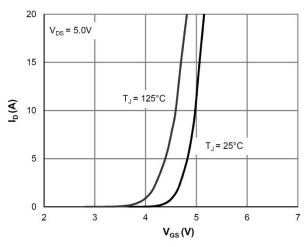
#### Note:

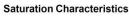
1. The test condition is VDD=50V,VGS=10V,L=0.5mH,RG=25 $\Omega$ ;

#### 200V N-Channel Power MOSFET

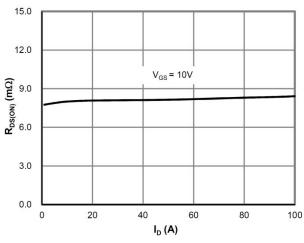
### **Typical Characteristics**

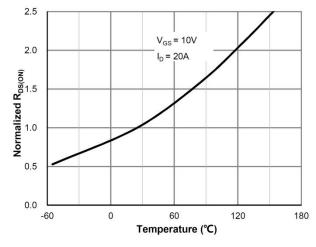






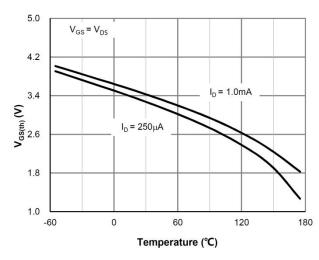


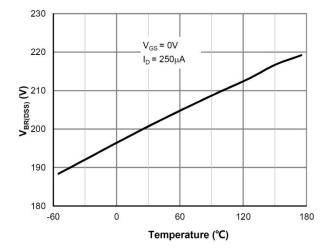




R<sub>DS(ON)</sub> vs. Drain Current

 $R_{\mathrm{DS(ON)}}$  vs. Junction Temperature

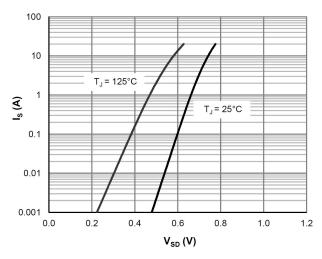


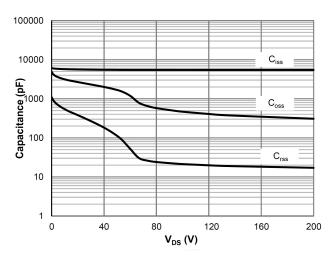


 $V_{\text{GS(th)}}$  vs. Junction Temperature

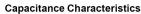
 $\mathbf{V}_{\text{BR}(\text{DSS})}$  vs. Junction Temperature

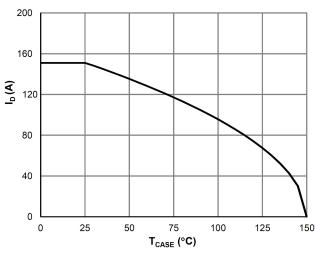


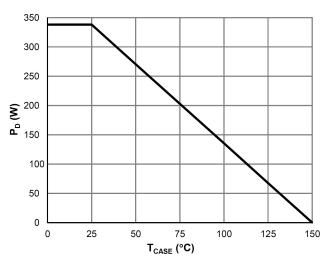




**Body-Diode Characteristics** 

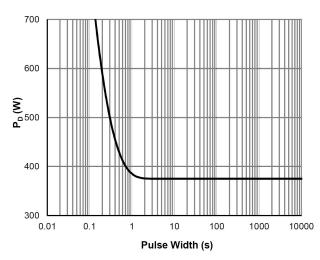


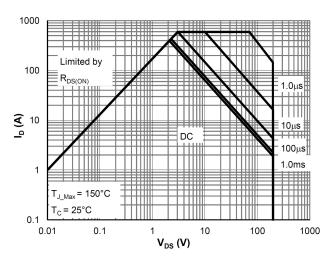




**Current De-rating** 

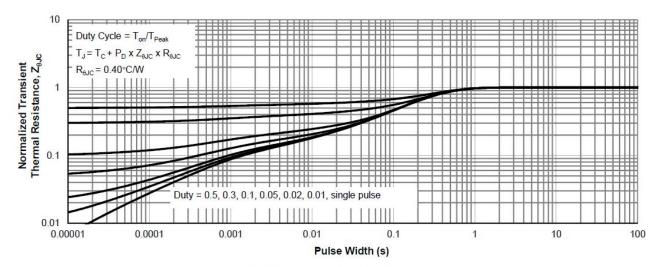
Power De-rating





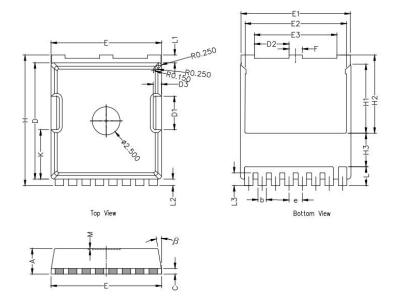
Single Pulse Power Rating, Junction-to-Case

**Maximum Safe Operating Area** 



Normalized Maximum Transient Thermal Impedance

# TOLL Package Information



Symbol	Dimensions In Millimeters			
	Min.	Nom.	Max.	
A	2.20	2.30	2.40	
b	0.65	0.75	0.85	
С	0.508 REF			
D	10.25	10.40	10.55	
D1	2.85	3.00	3.15	
E	9.75	9.90	10.05	
E1	9.65	9.80	9.95	
E2	8.95	9.10	9.25	
E3	7.25	7.40	7.55	
е	1.20 BSC			
F	1.05	1.20	1.35	
Н	11.55	11.70	11.85	
H1	6.03	6.18	6.33	
H2	6.85	7.00	7.15	
H3	3.00 BSC			
L	1.55	1.70	1.85	
L1	0.55	0.7	0.85	
L2	0.45	0.6	0.75	
M	0.08 REF.			
β	8°	10°	12°	
K	4.25	4.40	4.55	